# **BLP05H6350XR**; BLP05H6350XRG Power LDMOS transistor

**AMPLEON** 

Rev. 4 — 21 September 2016

Product data sheet

## **Product profile**

#### 1.1 General description

A 350 W extremely rugged LDMOS power transistor for broadcast and industrial applications in the HF to 600 MHz band.

Table 1. **Application information** 

Test signal	f	V <sub>DS</sub>	P <sub>L</sub>	G <sub>p</sub>	η <sub>D</sub>
	(MHz)	(V)	(W)	(dB)	(%)
pulsed RF	108	50	350	27	75

#### 1.2 Features and benefits

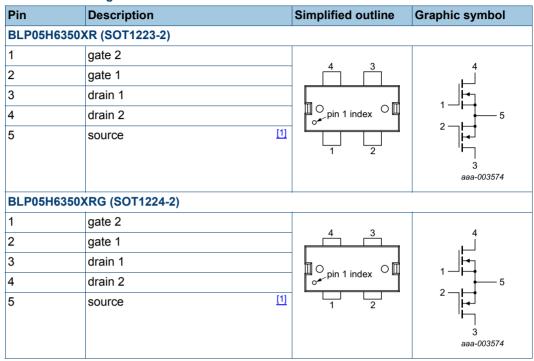
- Easy power control
- Integrated ESD protection
- Excellent ruggedness
- High efficiency
- Excellent thermal stability
- Designed for broadband operation (HF to 600 MHz)
- Compliant to Directive 2002/95/EC, regarding Restriction of Hazardous Substances (RoHS)

#### 1.3 Applications

- Industrial, scientific and medical applications
- Broadcast transmitter applications

# 2. Pinning information

Table 2. Pinning



[1] Connected to flange.

# 3. Ordering information

Table 3. Ordering information

Type number	Package	ackage		
	Name	Description	Version	
BLP05H6350XR	HSOP4F	plastic, heatsink small outline package; 4 leads (flat)	SOT1223-2	
BLP05H6350XRG	HSOP4F	plastic, heatsink small outline package; 4 leads	SOT1224-2	

# 4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{DS}$	drain-source voltage		-	135	V
$V_{GS}$	gate-source voltage		-6	+11	V
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature	[1]	-	225	°C

<sup>[1]</sup> Continuous use at maximum temperature will affect the reliability, for details refer to the online MTF calculator.

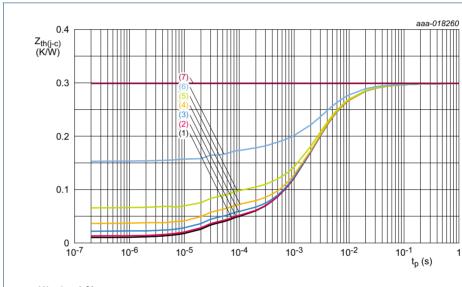
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## 5. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions		Тур	Unit
R <sub>th(j-c)</sub>	thermal resistance from junction to case	T <sub>j</sub> = 115 °C	[1][2]	0.30	K/W
Z <sub>th(j-c)</sub>	transient thermal impedance from junction to case	$T_j$ = 150 °C; $t_p$ = 100 μs; $\delta$ = 20 %	[3]	0.098	K/W

- [1]  $T_i$  is the junction temperature.
- [2]  $R_{th(j-c)}$  is measured under RF conditions.
- [3] See Figure 1.



- (1)  $\delta = 1 \%$
- (2)  $\delta = 2 \%$
- (3)  $\delta = 5 \%$
- (4)  $\delta = 10 \%$
- (5)  $\delta = 20 \%$
- (6)  $\delta = 50 \%$
- (7)  $\delta = 100 \% (DC)$

Fig 1. Transient thermal impedance from junction to case as a function of pulse duration

## 6. Characteristics

Table 6. DC characteristics

 $T_j = 25$  °C; per section unless otherwise specified.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V <sub>(BR)DSS</sub>	drain-source breakdown voltage	$V_{GS} = 0 \text{ V}; I_D = 1.5 \text{ mA}$	135	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	$V_{DS}$ = 10 V; $I_{D}$ = 150 mA	1.33	2.0	2.33	٧
$V_{GSq}$	gate-source quiescent voltage	$V_{DS}$ = 50 V; $I_{D}$ = 50 mA	-	1.9	-	V

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Table 6. DC characteristics ...continued

 $T_i$  = 25 °C; per section unless otherwise specified.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
I <sub>DSS</sub>	drain leakage current	V <sub>GS</sub> = 0 V; V <sub>DS</sub> = 50 V	-	-	1.4	μΑ
I <sub>DSX</sub>	drain cut-off current	$V_{GS} = V_{GS(th)} + 3.75 \text{ V};$ $V_{DS} = 10 \text{ V}$	-	21	-	A
I <sub>GSS</sub>	gate leakage current	V <sub>GS</sub> = 11 V; V <sub>DS</sub> = 0 V	-	-	140	nA
R <sub>DS(on)</sub>	drain-source on-state resistance	$V_{GS} = V_{GS(th)} + 3.75 \text{ V};$ $I_D = 5.25 \text{ A}$	-	0.29	-	Ω

#### Table 7. AC characteristics

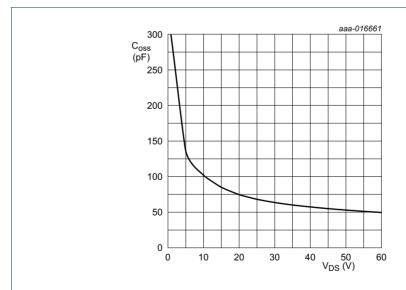
 $T_i$  = 25 °C; per section unless otherwise specified.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
C <sub>rs</sub>	feedback capacitance	V <sub>GS</sub> = 0 V; V <sub>DS</sub> = 50 V; f = 1 MHz	-	1.3	-	pF
C <sub>iss</sub>	input capacitance	V <sub>GS</sub> = 0 V; V <sub>DS</sub> = 50 V; f = 1 MHz	-	161	-	pF
Coss	output capacitance	V <sub>GS</sub> = 0 V; V <sub>DS</sub> = 50 V; f = 1 MHz	-	53	-	pF

#### Table 8. RF characteristics

Test signal: pulsed RF;  $t_p$  = 100  $\mu$ s;  $\delta$  = 20 %; f = 108 MHz; RF performance at  $V_{DS}$  = 50 V;  $I_{Dq}$  = 100 mA;  $T_{case}$  = 25 °C; unless otherwise specified; in a class-AB production test circuit.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Gp	power gain	P <sub>L</sub> = 350 W	26.5	27.5	-	dB
RLin	input return loss	P <sub>L</sub> = 350 W	-	-10	-	dB
$\eta_{D}$	drain efficiency	P <sub>L</sub> = 350 W	71	75	-	%



 $V_{GS} = 0 V$ ; f = 1 MHz.

Fig 2. Output capacitance as a function of drain-source voltage; typical values per section

## 7. Test information

## 7.1 Ruggedness in class-AB operation

The BLP05H6350XR and BLP05H6350XRG are capable of withstanding a load mismatch corresponding to VSWR > 65 : 1 through all phases under the following conditions:  $V_{DS} = 50 \text{ V}$ ;  $I_{Dq} = 100 \text{ mA}$ ;  $P_L = 350 \text{ W}$  pulsed; f = 108 MHz.

#### 7.2 Impedance information

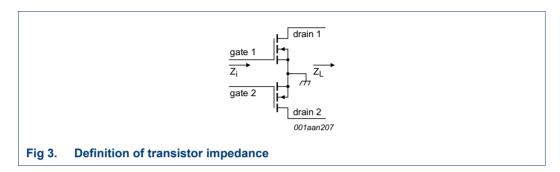


Table 9. Typical push-pull impedance

Simulated  $Z_i$  and  $Z_L$  device impedance; impedance info at  $V_{DS}$  = 50 V and  $P_L$  = 350 W.

f	Z <sub>i</sub>	Z <sub>L</sub>
(MHz)	(Ω)	(Ω)
108	10.6 – j36.2	10.8 + j2.5

## 7.3 UIS avalanche energy

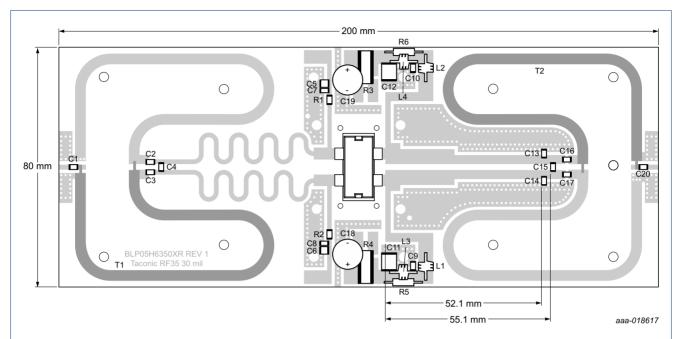
#### Table 10. Typical avalanche data per section

 $T_{amb}$  = 25 °C; typical test data; test jig without water cooling.

I <sub>AS</sub>	E <sub>AS</sub>
(A)	(J)
10	1.8
12.5	1.3
15	0.9

For information see application note AN10273.

#### 7.4 Test circuit



Printed-Circuit Board (PCB): Taconic RF-35;  $\epsilon_r$  = 3.5 F/m; thickness = 0.765 mm; thickness copper plating = 35  $\mu$ m, gold plated.

See Table 11 for a list of components.

Fig 4. Component layout for class-AB production test circuit

Table 11. List of components

For test circuit see Figure 4.

Component	Description	Value	Remarks
C1, C4	multilayer ceramic chip capacitor	51 pF [1]	
C2, C3	multilayer ceramic chip capacitor	150 pF [1]	
C5, C6	multilayer ceramic chip capacitor	4.7 μF, 50 V	
C7, C8	multilayer ceramic chip capacitor	820 pF [1]	
C9, C10	multilayer ceramic chip capacitor	820 pF [1]	
C11, C12	multilayer ceramic chip capacitor	4.7 μF, 100 V	
C13, C14	multilayer ceramic chip capacitor	62 pF [1]	
C15	electrolytic capacitor	7.5 pF [1]	
C16, C17	multilayer ceramic chip capacitor	110 pF [1]	
C18,C19	electrolytic capacitor	2200 μF, 64 V	
C20	multilayer ceramic chip capacitor	51 pF [1]	
L1, L2, L3, L4	wire inductor	3 turns, D = 3 mm, 1 mm copper wire	
R1, R2	resistor	510 Ω	SMD 1206
R3, R4	shunt resistor	0.01 Ω	Ohmite: FC4L110R010FER
R5, R6	metal film resistor	10 Ω, 0.6 W	
T1, T2	semi rigid coax	$50 \Omega$ , length = 160 mm	EZ Form: EZ-141-AL-TP-M17

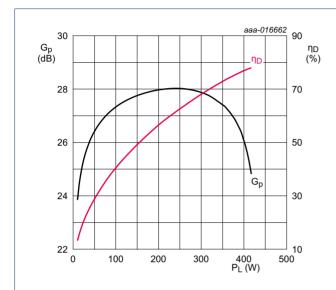
[1] American Technical Ceramics type 100B or capacitor of same quality.

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#### 7.5 Graphical data

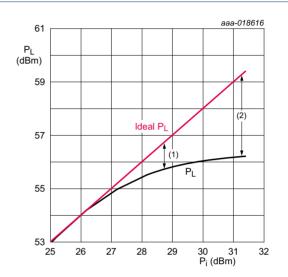
The following figures are measured in a class-AB production test circuit.

#### 7.5.1 1-Tone CW pulsed



 $V_{DS}$  = 50 V;  $I_{Dq}$  = 100 mA; f = 108 MHz;  $t_p$  = 100  $\mu s;$   $\delta$  = 20 %.

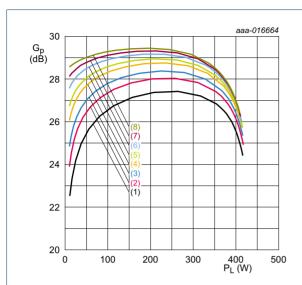
Fig 5. Power gain and drain efficiency as function of output power; typical values



 $V_{DS}$  = 50 V;  $I_{Dq}$  = 100 mA; f = 108 MHz;  $t_p$  = 100  $\mu s;$   $\delta$  = 20 %.

- (1)  $P_{L(1dB)} = 55.7 \text{ dBm } (372 \text{ W})$
- (2)  $P_{L(3dB)} = 56.2 \text{ dBm } (415 \text{ W})$

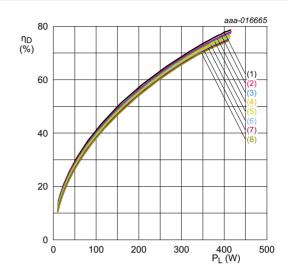
Fig 6. Output power as a function of input power; typical values



 $V_{DS}$  = 50 V; f = 108 MHz;  $t_p$  = 100  $\mu$ s;  $\delta$  = 20 %.

- (1)  $I_{Dq} = 20 \text{ mA}$
- (2)  $I_{Dq} = 100 \text{ mA}$
- (3)  $I_{Dq} = 200 \text{ mA}$
- (4)  $I_{Dq} = 400 \text{ mA}$
- (5)  $I_{Dq} = 600 \text{ mA}$
- (6)  $I_{Dq} = 800 \text{ mA}$
- (7)  $I_{Dq} = 1000 \text{ mA}$
- (8)  $I_{Dq} = 1200 \text{ mA}$

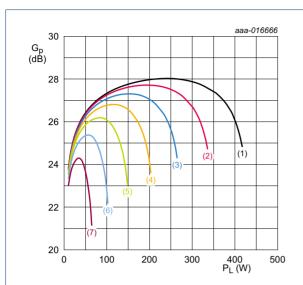
Fig 7. Power gain as a function of output power; typical values



 $V_{DS}$  = 50 V; f = 108 MHz;  $t_p$  = 100  $\mu$ s;  $\delta$  = 20 %.

- (1)  $I_{Dq} = 20 \text{ mA}$
- (2)  $I_{Dq} = 100 \text{ mA}$
- (3)  $I_{Dq} = 200 \text{ mA}$
- (4)  $I_{Dq} = 400 \text{ mA}$
- (5)  $I_{Dq} = 600 \text{ mA}$
- (6)  $I_{Dq} = 800 \text{ mA}$
- (7)  $I_{Dq} = 1000 \text{ mA}$
- (8)  $I_{Dq} = 1200 \text{ mA}$

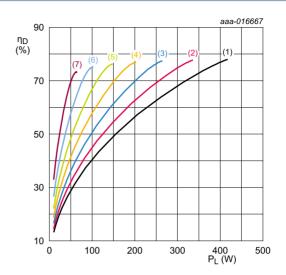
Fig 8. Drain efficiency as a function of output power; typical values



 $I_{Dq}$  = 100 mA; f = 108 MHz;  $t_p$  = 100  $\mu$ s;  $\delta$  = 20 %.

- (1)  $V_{DS} = 50 \text{ V}$
- (2)  $V_{DS} = 45 \text{ V}$
- (3)  $V_{DS} = 40 \text{ V}$
- (4)  $V_{DS} = 35 \text{ V}$
- (5)  $V_{DS} = 30 \text{ V}$
- (6)  $V_{DS} = 25 \text{ V}$
- (7)  $V_{DS} = 20 \text{ V}$

Fig 9. Power gain as a function of output power; typical values



 $I_{Dq}$  = 100 mA; f = 108 MHz;  $t_p$  = 100  $\mu$ s;  $\delta$  = 20 %.

- (1)  $V_{DS} = 50 \text{ V}$
- (2)  $V_{DS} = 45 \text{ V}$
- (3)  $V_{DS} = 40 \text{ V}$
- (4)  $V_{DS} = 35 V$
- (5)  $V_{DS} = 30 \text{ V}$
- (6)  $V_{DS} = 25 V$
- (7)  $V_{DS} = 20 \text{ V}$

Fig 10. Drain efficiency as a function of output power; typical values

# 8. Package outline

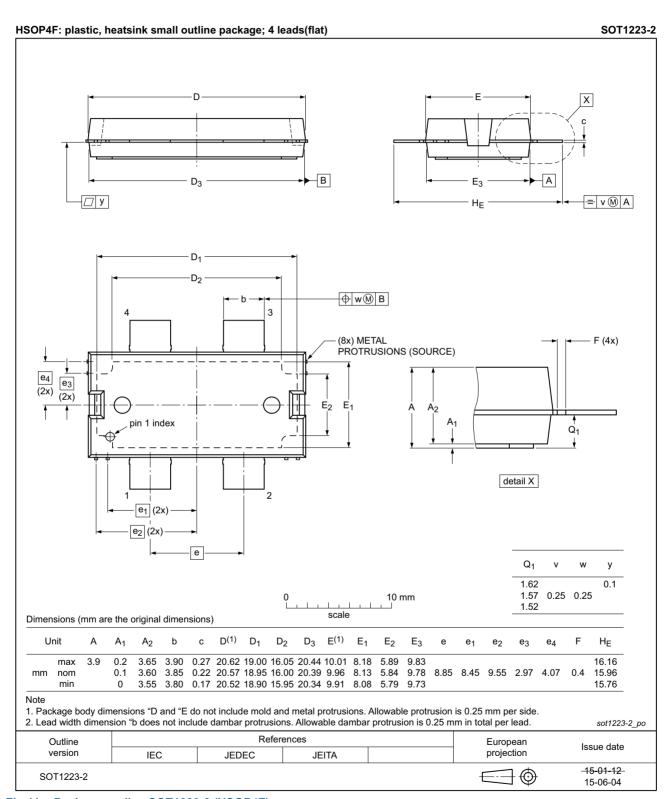


Fig 11. Package outline SOT1223-2 (HSOP4F)

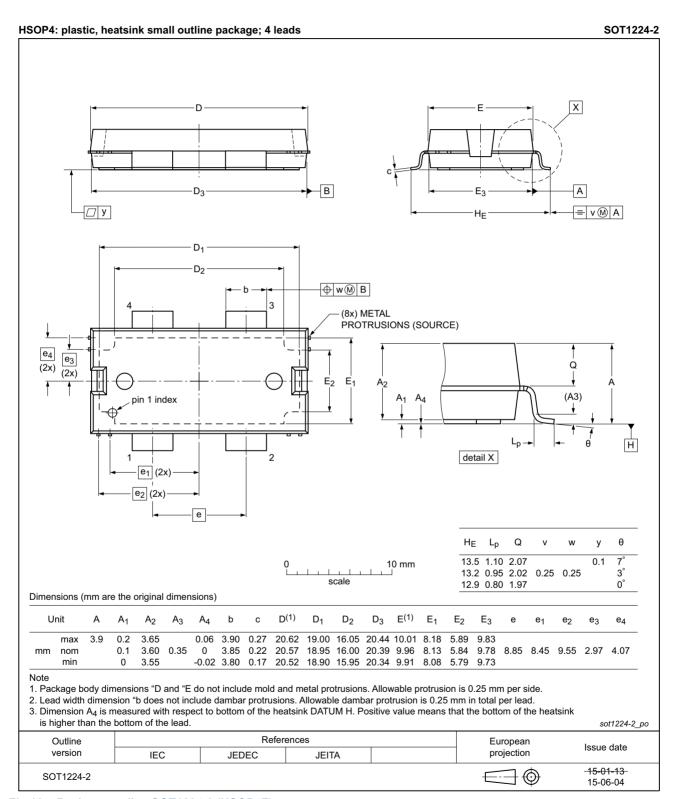


Fig 12. Package outline SOT1224-2 (HSOP4F)

# 9. Handling information

#### CAUTION



This device is sensitive to ElectroStatic Discharge (ESD). Observe precautions for handling electrostatic sensitive devices.

Such precautions are described in the ANSI/ESD S20.20, IEC/ST 61340-5, JESD625-A or equivalent standards.

# 10. Abbreviations

Table 12. Abbreviations

Acronym	Description	
CW	Continuous Wave	
ESD	ElectroStatic Discharge	
HF	High Frequency	
LDMOS	Laterally Diffused Metal-Oxide Semiconductor	
MTF	Median Time to Failure	
SMD	Surface Mounted Device	
UIS	Unclamped Inductive Switching	
VSWR	Voltage Standing-Wave Ratio	

# 11. Revision history

Table 13. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes	
BLP05H6350XR_H6350XRG v.4	20160921	Product data sheet	-	BLP05H6350XR v.3	
Modifications:	<ul> <li>The document now describes both the straight lead and gull-wing versions of this product: BLP05H6350XR and BLP05H6350XRG respectively</li> </ul>				
	<ul> <li><u>Table 2 on page 2</u>: added BLP05H6350XRG data</li> </ul>				
	<ul> <li><u>Table 3 on page 2</u>: added BLP05H6350XRG data</li> </ul>				
	Section 7.1 on page 5: added BLP05H6350XRG				
	• Figure 12 on page 11: added figure SOT1224-2				
BLP05H6350XR v.3	20151012	Product data sheet	-	BLP05H6350XR#2	
BLP05H6350XR#2	20150901	Preliminary data sheet	-	BLP05H6350XR v.1	
BLP05H6350XR v.1	20150703	Preliminary data sheet	-	-	

# 12. Legal information

#### 12.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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Product [short] data sheet	Production	This document contains the product specification.

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- [2] The term 'short data sheet' is explained in section "Definitions"
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# **BLP05H6350XR; BLP05H6350XRG**

**Power LDMOS transistor** 

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